

September 2009

H11N1M, H11N2M, H11N3M 6-Pin DIP High Speed Logic Optocouplers

Features

- High data rate, 5MHz typical (NRZ)
- Free from latch up and oscilliation throughout voltage and temperature ranges.
- Microprocessor compatible drive
- Logic compatible output sinks 16mA at 0.5V maximum
- Guaranteed on/off threshold hysteresis
- Wide supply voltage capability, compatible with all popular logic systems
- High common mode transient immunity, 2000V/µs minimum
- Fast switching $t_r = 7.5$ ns typical, $t_f = 12$ ns typical
- Underwriter Laboratory (UL) recognized file #E90700
- VDE recognized—File#102497 Add option V (e.g., H11N1VM)

Applications

- Logic to logic isolator
- Programmable current level sensor
- Line receiver—eliminate noise and transient problems
- A.C. to TTL conversion—square wave shaping
- Interfaces computers with peripherals
- Isolated power MOS driver for power supplies

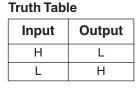
Description

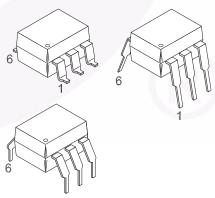
The H11NXM series has a high speed integrated circuit detector optically coupled to an AlGaAs infrared emitting diode. The output incorporates a Schmitt trigger, which provides hysteresis for noise immunity and pulse shaping. The detector circuit is optimized for simplicity of operation and utilizes an open collector output for maximum application flexibility.

Schematic

ANODE 1 CATHODE 2 S GND 4 Vo

Package Outlines





Absolute Maximum Ratings (T_A = 25°C unless otherwise specified.)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Value	Units
TOTAL DEVIC			
T _{STG}	Storage Temperature	-40 to +150	°C
T _{OPR}	Operating Temperature	-40 to +85	°C
T _{SOL}	Lead Solder Temperature	260 for 10 sec	°C
P _D	Total Device Power Dissipation @ 25°C	250	mW
	Derate Above 25°C	2.94	mW/°C
EMITTER			
I _F	Continuous Forward Current	30	mA
V _R	Reverse Voltage	6	V
I _F (pk)	Forward Current – Peak (1µs pulse, 300 pps)	1.0	А
P _D	LED Power Dissipation 25°C Ambient	120	mW
	Derate Linearly From 25°C	1.41	mW/°C
DETECTOR			
P _D	Detector Power Dissipation @ 25°C	150	mW
	Derate Linearly from 25°C	1.76	mW/°C
Vo	V ₄₅ Allowed Range	0 to 16	V
V _{CC}	V ₆₅ Allowed Range	0 to 16	V
Io	I ₄ Output Current	50	mA

$\textbf{Electrical Characteristics} \; (T_{A} = 25^{\circ}\text{C unless otherwise specified.})$

Individual Component Characteristics

Symbol	Parameters	Test Conditions	Device	Min.	Тур.*	Max.	Units
EMITTER	EMITTER						
V _F	Input Forward Voltage	I _F = 10mA	All		1.4	2	V
		I _F = 0.3mA		0.75	1.25		
I _R	Reverse Current	V _R = 5V	All			10	μA
CJ	Capacitance	V = 0, f = 1.0MHz	All			100	pF
DETECTO	DETECTOR						
V _{CC}	Operating Voltage Range		All	4		15	V
I _{CC(off)}	Supply Current	I _F = 0, V _{CC} = 5V	All		6	10	mA
I _{OH}	Output Current, High	$I_F = 0.3 \text{mA}, V_{CC} = V_O = 15 \text{V}$	All			100	μA

Transfer Characteristics

Symbol	DC Characteristics	Test Conditions	Device	Min.	Тур.*	Max.	Units
I _{CC(on)}	Supply Current	I _F = 10mA, V _{CC} = 5V	All		6.5	10	mA
V _{OL}	Output Voltage, Low	R_L =270 Ω , V_{CC} =5 V ,	All	\\.		0.5	V
		$I_F = I_{F(on)} \text{ max.}$					
I _{F(on)}	Turn-On Threshold Current	$R_L = 270\Omega, V_{CC} = 5V^{(1)}$	H11N1M	0.8		3.2	mA
			H11N2M	2.3		5	
			H11N3M	4.1		10	
I _{F(off)}	Turn-Off Threshold Current	$R_L = 270\Omega, V_{CC} = 5V$	All	0.3			mA
I _{F(off)} / I _{F(on)}	Hysteresis Ratio	$R_L = 270\Omega, V_{CC} = 5V$	All	0.65		0.95	

Switching Speed

Symbol	AC Characteristics	Test Conditions	Device	Min.	Тур.*	Max.	Units
t _{PHL}	Propagation Delay Time HIGH-to-LOW	C = 120pF, t_P = 1 μ s, R _E = ⁽²⁾ , Figure 1	All		100	330	ns
t _r	Rise Time	C = 120pF, t_P = 1 μ s, R_E = $^{(2)}$, Figure 1	All		7.5		ns
t _{PLH}	Propagation Delay Time LOW-to-HIGH	C = 120pF, t_P = 1 μ s, R_E = $^{(2)}$, Figure 1	All		150	330	ns
t _f	Fall Time	C = 120pF, t_P = 1 μ s, R_E = $^{(2)}$, Figure 1	All		12		ns
	Data Rate		All		5		MHz

Isolation Characteristics

Symbol	Parameters	Test Conditions	Min.	Тур.*	Max.	Units
V _{ISO}	Input-Output Isolation Voltage	f = 60 Hz, t =1 sec.	7500			V _{PEAK}
C _{ISO}	Isolation Capacitance	V _{I-O} = 0V, f = 1 MHz		0.4	0.6	pF
R _{ISO}	Isolation Resistance	V _{I-O} = ±500 VDC	10 ¹¹			Ω

^{*}Typical values at $T_A = 25$ °C

Notes:

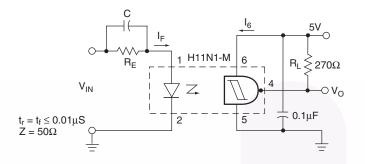
- 1. Maximum I_{F(ON)} is the maximum current required to trigger the output. For example, a 3.2mA maximum trigger current would require the LED to be driven at a current greater than 3.2mA to guarantee the device will turn on. A 10% guard band is recommended to account for degradation of the LED over its lifetime. The maximum allowable LED drive current is 30mA.
- 2. H11N1: R_E = 910 Ω , H11N2: R_E = 560 Ω , H11N3: R_E = 240 Ω

Safety and Insulation Ratings

As per IEC 60747-5-2, this optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Symbol	Parameter	Min.	Тур.	Max.	Unit
	Installation Classifications per DIN VDE 0110/1.89 Table 1				
	For Rated Main Voltage < 150Vrms		I-IV		
	For Rated Main voltage < 300Vrms		I-IV		
	Climatic Classification		55/100/21		
	Pollution Degree (DIN VDE 0110/1.89)		2		
CTI	Comparative Tracking Index	175			
V _{PR}	Input to Output Test Voltage, Method b, V _{IORM} x 1.875 = V _{PR} , 100% Production Test with tm = 1 sec, Partial Discharge < 5pC	1594			V _{peak}
	Input to Output Test Voltage, Method a, V _{IORM} x 1.5 = V _{PR} , Type and Sample Test with tm = 60 sec, Partial Discharge < 5pC	1275			V _{peak}
V _{IORM}	Max. Working Insulation Voltage	850			V _{peak}
V _{IOTM}	Highest Allowable Over Voltage	6000			V _{peak}
	External Creepage	7			mm
	External Clearance	7			mm
	Insulation Thickness	0.5			mm
RIO	Insulation Resistance at Ts, V _{IO} = 500V	10 ⁹			Ω

Typical Performance Curves



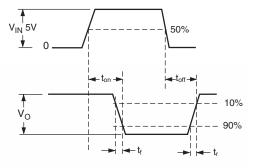
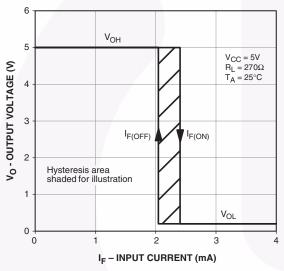


Figure 1. Switching Test Circuit and Waveforms

Figure 2. Transfer Characteristics



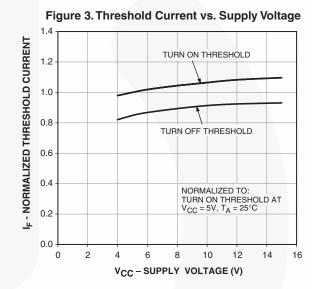
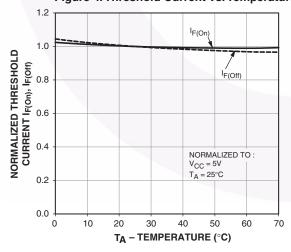
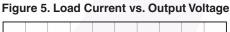
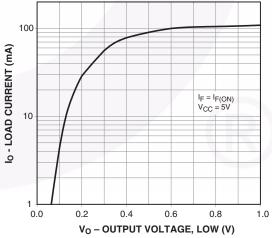


Figure 4. Threshold Current vs. Temperature







Typical Performance Curves (Continued)

Figure 6. Supply Current vs. Supply Voltage

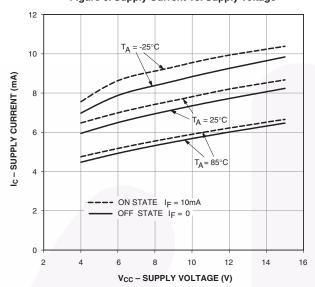
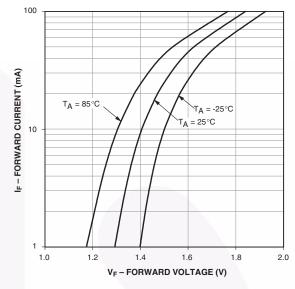
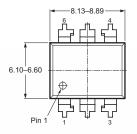


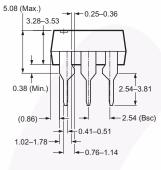
Figure 7. LED Forward Voltage vs. Forward Current

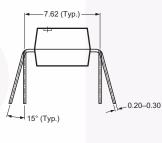


Package Dimensions

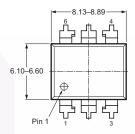
Through Hole

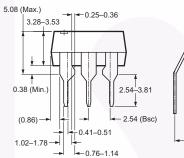


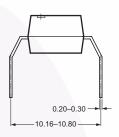




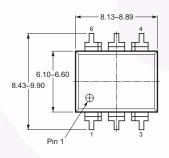
0.4" Lead Spacing

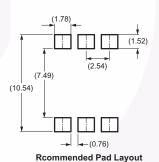


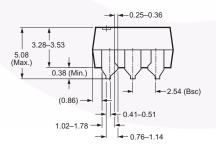


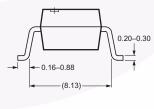


Surface Mount







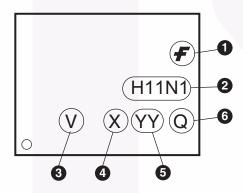


Note: All dimensions in mm.

Ordering Information

Option	Order Entry Identifier (Example)	Description		
No option	H11N1M	Standard Through Hole Device		
S	H11N1SM	Surface Mount Lead Bend		
SR2	H11N1SR2M	Surface Mount; Tape and Reel		
Т	H11N1TM	0.4" Lead Spacing		
V	H11N1VM	VDE 0884		
TV	H11N1TVM	VDE 0884, 0.4" Lead Spacing		
SV	H11N1SVM	VDE 0884, Surface Mount		
SR2V	H11N1SR2VM	VDE 0884, Surface Mount, Tape and Reel		

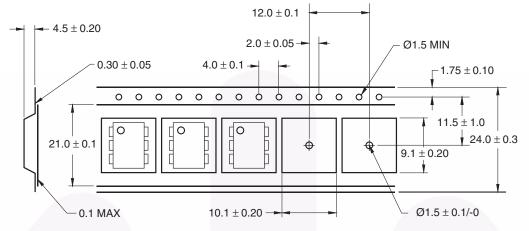
Marking Information



Definiti	Definitions						
1	Fairchild logo						
2	Device number						
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)						
4	One digit year code, e.g., '3'						
5	Two digit work week ranging from '01' to '53'						
6	Assembly package code						

^{*}Note – Parts that do not have the 'V' option (see definition 3 above) that are marked with date code '325' or earlier are marked in portrait format.

Tape Dimensions

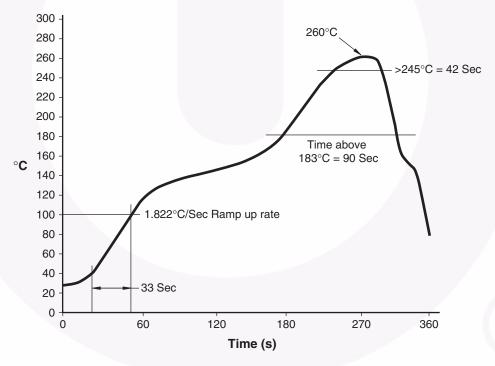


User Direction of Feed ----

Note:

All dimensions are in millimeters.

Reflow Soldering Profile







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